

## 40V N-Channel MOSFETs

### General Description

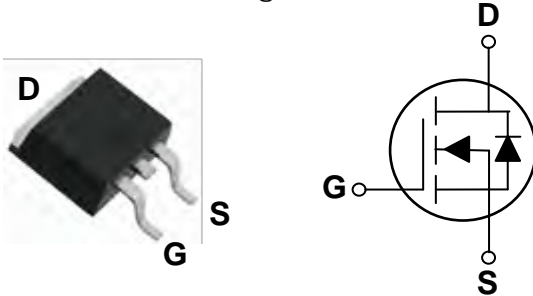
These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize onstate resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

BVDSS	RDSON	ID
40V	3.8mΩ	90A

### Features

- 40V, 90A, RDS(ON) = 3.8mΩ @ VGS = 10V
- Improved dv/dt capability
- Fast switching
- Green Device Available

### TO-252 Pin Configuration



### Applications

- MB / VGA / Vcore
- POL Applications
- SMPS 2<sup>nd</sup> SR

### Absolute Maximum Ratings (Tc=25 °C unless otherwise noted)

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	40	V
V <sub>GS</sub>	Gate-Source Voltage	± 20	V
I <sub>D</sub>	Drain Current – Continuous (T <sub>C</sub> =25 °C)	90	A
	Drain Current – Continuous (T <sub>C</sub> =100 °C)	57	A
I <sub>DM</sub>	Drain Current – Pulsed <sup>1</sup>	360	A
EAS	Single Pulse Avalanche Energy <sup>2</sup>	312	mJ
IAS	Single Pulse Avalanche Current <sup>2</sup>	79	A
P <sub>D</sub>	Power Dissipation (T <sub>C</sub> =25 °C)	101	W
	Power Dissipation – Derate above 25 °C	0.81	W/°C
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction to ambient	---	62	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction to Case	---	1.23	°C/W



# FTK4960D

## Electrical Characteristics ( $T_J=25\text{ }^\circ\text{C}$ , unless otherwise noted)

### Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	40	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	$BV_{DSS}$ Temperature Coefficient	Reference to $25\text{ }^\circ\text{C}$ , $I_D=1mA$	---	0.03	---	V/ $^\circ\text{C}$
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=40V, V_{GS}=0V, T_J=25\text{ }^\circ\text{C}$	---	---	1	$\mu A$
		$V_{DS}=32V, V_{GS}=0V, T_J=125\text{ }^\circ\text{C}$	---	---	10	$\mu A$
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	$\pm 100$	nA

### On Characteristics

$R_{DS(ON)}$	Static Drain-Source On-Resistance <sup>3</sup>	$V_{GS}=10V, I_D=25A$	---	3.1	3.8	m $\Omega$
		$V_{GS}=4.5V, I_D=12A$	---	4.0	5.0	m $\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\mu A$	1.2	1.6	2.5	V
$\Delta V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	-5	---	mV/ $^\circ\text{C}$
$g_{fs}$	Forward Transconductance	$V_{DS}=10V, I_D=2A$	---	16	---	S

### Dynamic and switching Characteristics

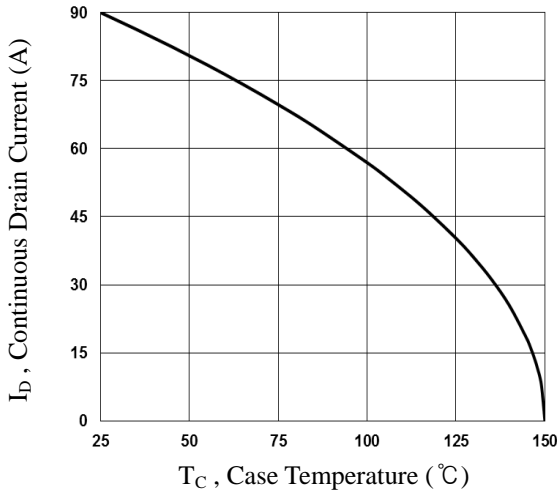
$Q_g$	Total Gate Charge <sup>3,4</sup>	$V_{DS}=20V, V_{GS}=4.5V, I_D=10A$	---	44.4	80	nC
$Q_{gs}$	Gate-Source Charge <sup>3,4</sup>		---	9.6	18	
$Q_{gd}$	Gate-Drain Charge <sup>3,4</sup>		---	16	30	
$T_{d(on)}$	Turn-On Delay Time <sup>3,4</sup>	$V_{DD}=20V, V_{GS}=10V, R_G=6\Omega$ $I_D=1A$	---	28	50	ns
$T_r$	Rise Time <sup>3,4</sup>		---	3.2	6.5	
$T_{d(off)}$	Turn-Off Delay Time <sup>3,4</sup>		---	89	160	
$T_f$	Fall Time <sup>3,4</sup>		---	14	28	
$C_{iss}$	Input Capacitance	$V_{DS}=25V, V_{GS}=0V, F=1MHz$	---	4940	7800	pF
$C_{oss}$	Output Capacitance		---	425	800	
$C_{rss}$	Reverse Transfer Capacitance		---	170	330	
$R_g$	Gate resistance	$V_{GS}=0V, V_{DS}=0V, F=1MHz$	---	1.4	2.8	$\Omega$

### Drain-Source Diode Characteristics and Maximum Ratings

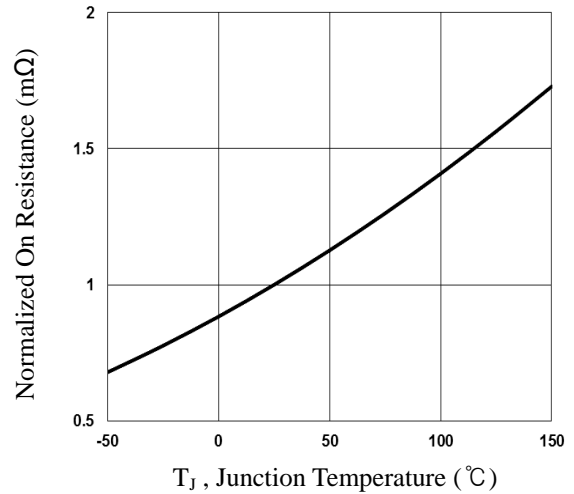
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_S$	Continuous Source Current	$V_G=V_D=0V$ , Force Current	---	---	90	A
$I_{SM}$	Pulsed Source Current <sup>3</sup>		---	---	180	A
$V_{SD}$	Diode Forward Voltage <sup>3</sup>	$V_{GS}=0V, I_S=1A, T_J=25\text{ }^\circ\text{C}$	---	---	1	V

Note :

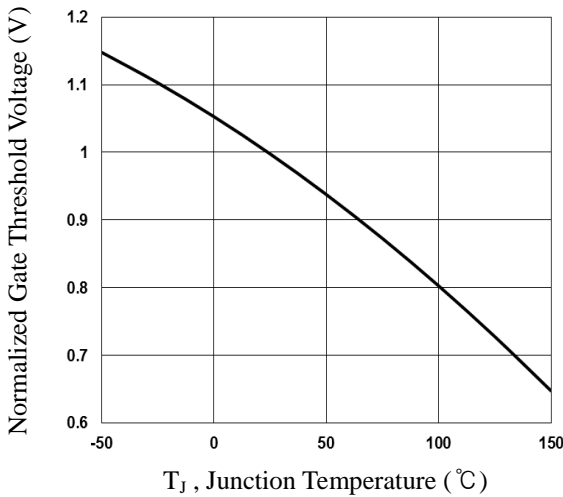
1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2.  $V_{DD}=25V, V_{GS}=10V, L=0.1mH, I_{AS}=79A$ , Starting  $T_J=25\text{ }^\circ\text{C}$
3. The data tested by pulsed , pulse width  $\leq 300\mu s$  , duty cycle  $\leq 2\%$ .
4. Essentially independent of operating temperature.



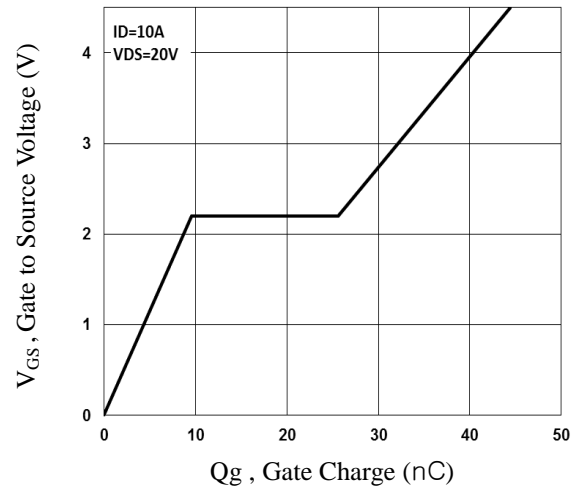
**Fig.1 Continuous Drain Current vs.  $T_C$**



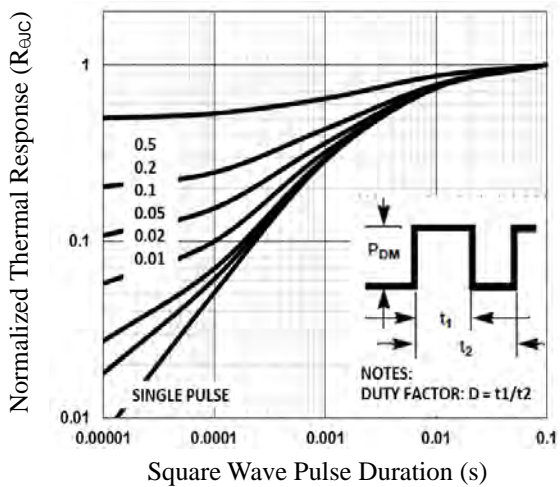
**Fig.2 Normalized  $R_{DS(on)}$  vs.  $T_J$**



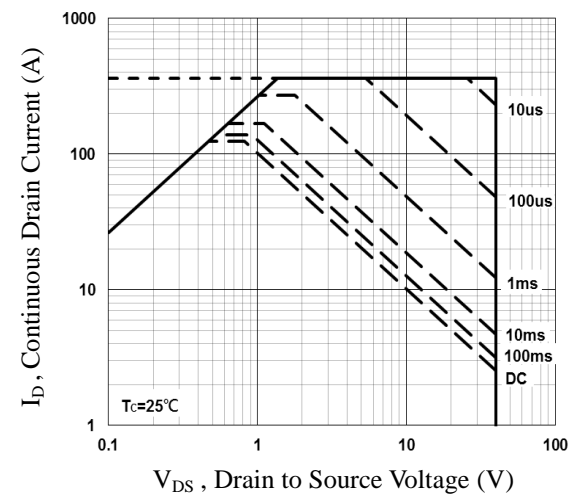
**Fig.3 Normalized  $V_{th}$  vs.  $T_J$**



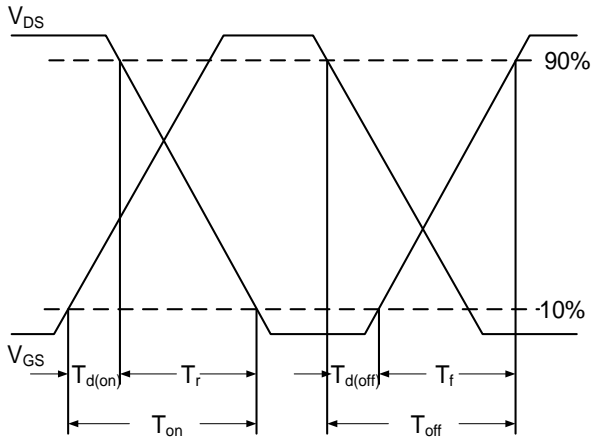
**Fig.4 Gate Charge Waveform**



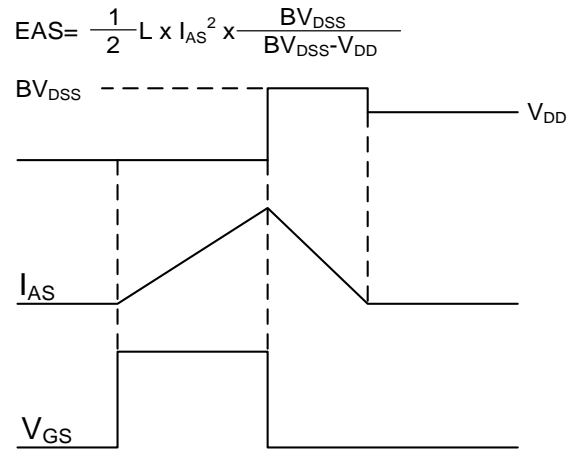
**Fig.5 Normalized Transient Impedance**



**Fig.6 Maximum Safe Operation Area**

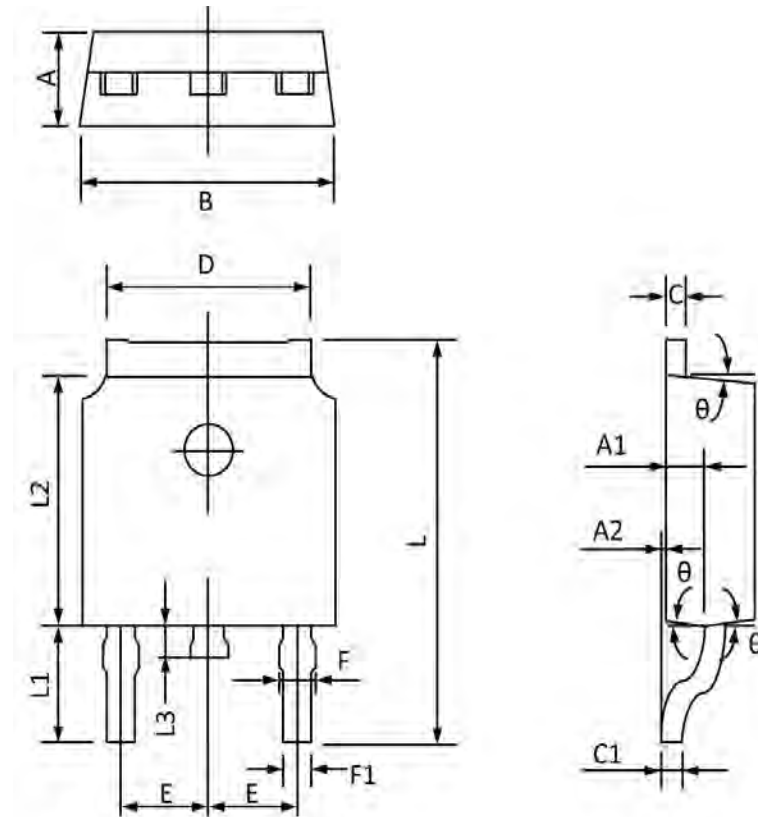


**Fig. 7 Switching Time Waveform**



**Fig. 8 EAS Waveform**

## TO-252 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	2.400	2.200	0.094	0.087
A1	1.110	0.910	0.044	0.036
A2	0.150	0.000	0.006	0.000
B	6.800	6.400	0.268	0.252
C	0.580	0.450	0.023	0.018
C1	0.580	0.460	0.023	0.018
D	5.500	5.100	0.217	0.201
E	2.386	2.186	0.094	0.086
F	0.940	0.600	0.037	0.024
F1	0.860	0.500	0.034	0.020
L	10.400	9.400	0.409	0.370
L1	3.000	2.400	0.118	0.094
L2	6.200	5.400	0.244	0.213
L3	1.200	0.600	0.047	0.024
θ	9°	3°	9°	3°